

REV.	DESCRIPTION	DATE
A	RELEASE	Mar 15, 2013
B	2013072301	Jul 23, 2013

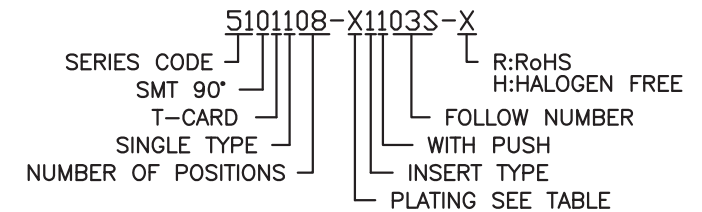
MATERIALS

1. HOUSING : HERMOPLASTIC (UL 94V-0) .
2. TERMINAL : COPPER ALLOY, PLATING SEE TABLE
3. SHELL : STEEL, NICKEL PLATED OVERALL.

SPECIFICATION

1. CURRENT RATING : 0.5 A. MAX.
2. DIELECTRIC WITHSTANDING VOLTAGE :
500V AC R.M.S. FOR 1 MINUTE.
3. INSULATION RESISTANCE :1000MΩ MIN.AT 250V DC.
4. CONTACT RESISTANCE : 100mΩ MAX.
5. OPERATING TEMPERATURE : -40°C TO +85°C.
6. MATIING DURABILITY : 10000 CACLES.

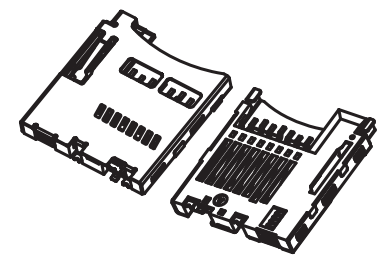
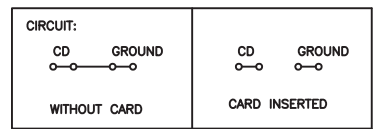
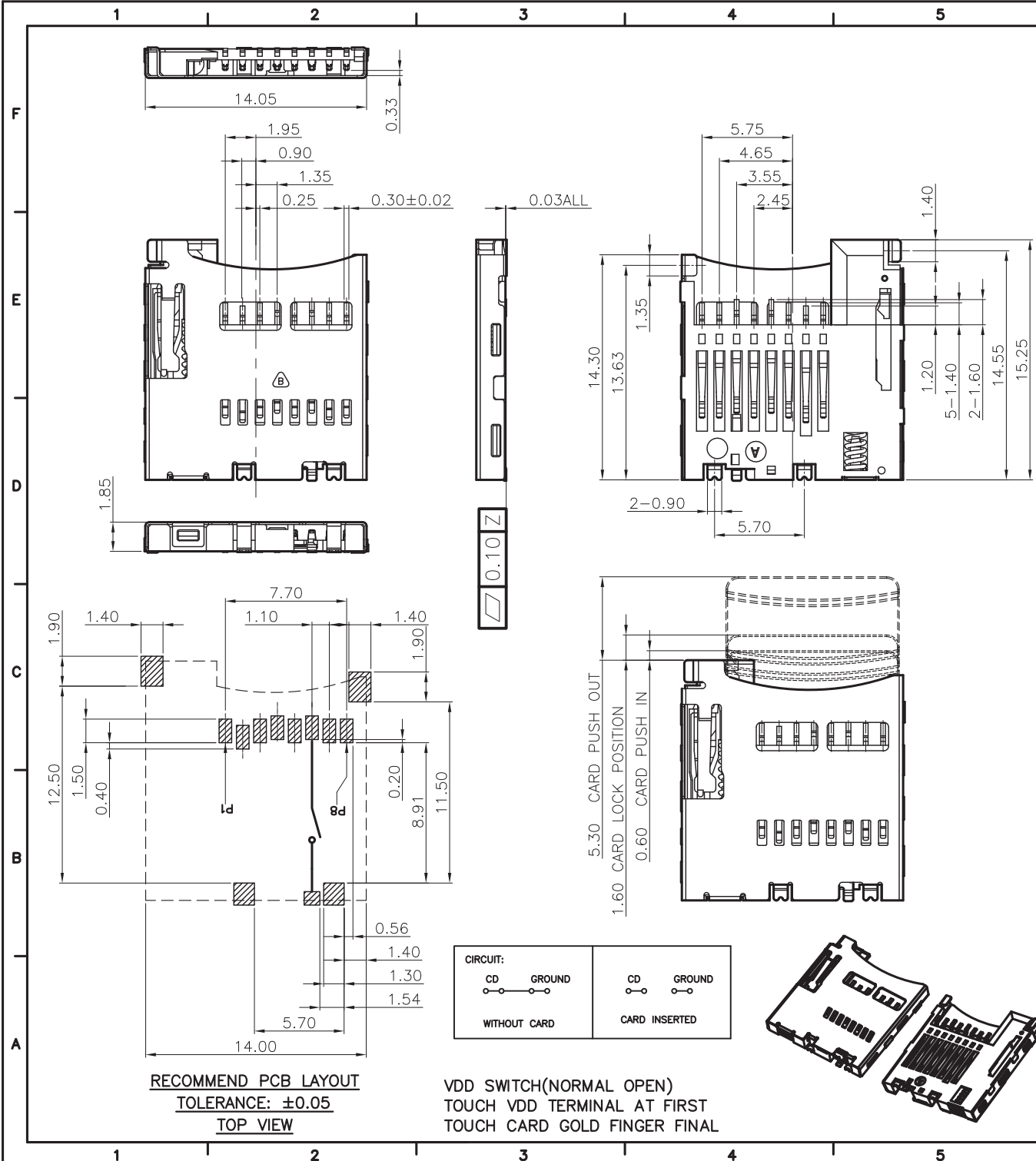
PART NUMBER INFORMATION :



PIN5	CLK	5P	PIN10	CARD DETECT	
PIN4	VDD	4P	PIN9		
PIN3	CMD	3P	PIN8	DAT1	8P
PIN2	CD/DAT3	2P	PIN7	DAT0	7P
PIN1	DAT2	1P	PIN6	VSS	6P
PIN NO.		MICRO SD	PIN NO.		MICRO SD

DESCRIPTION OF PLATING ON TERMINALS			
NO.	EXPLAIN	NO.	EXPLAIN
0	GOLD FLASH	3	GOLD 15u"
1	GOLD 5u"	4	GOLD 20u"
2	GOLD 10u"	6	GOLD 30u"

TOLERANCE .0=±0.25 .00=±0.15 .000=±0.05 ANG.=±3°	DRAWER 21 CHECK 21 APP'D XAWX	汉硕电子科技有限公司 NAME MICRO SD CARD PUSH CONN (内焊带检测PIN)
	PRODUCT SPEC. _____	
UNITS : mm 	SCALE NONE SIZE A7 SHEET 1 OF 1 REV. B	



RECOMMEND PCB LAYOUT
 TOLERANCE: ±0.05
 TOP VIEW

VDD SWITCH(NORMAL OPEN)
 TOUCH VDD TERMINAL AT FIRST
 TOUCH CARD GOLD FINGER FINAL